POWERSi

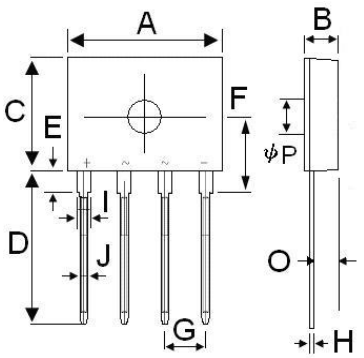
D3K2005~D3K210

Single Phase 2.0Amp Glass passivated Bridge Rectifiers

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 260℃/10 seconds at terminals

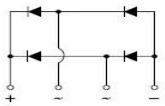
D3K



D3K		
DIM	MIN	MAX
A	14.20	14.70
B	3.30	3.60
C	10.20	10.60
D	13.80	14.40
E	1.85	2.25
F	6.65	7.25
G	3.71	3.91
H	0.30	0.55
I	1.25	1.55
J	0.78	0.88
O	1.80	2.40
P	3.0Φ	3.4Φ
All dimension in millimeter		

Mechanical Data

Case : Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any



Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	D3K 2005	D3K 201	D3K 202	D3K 204	D3K 206	D3K 208	D3K 210	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current with heatsink	$I_{(AV)}$	2.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	60.0							A
Rating for fusing (t=8.3ms, Ta=25℃)	I^2t	14.94							A^2s
Maximum instantaneous forward voltage at 1.0A	V_F	1.10							V
Maximum DC reverse current T_A =25℃ at rated DC blocking voltage T_A=125℃	I_R	5.0 500							uA
Typical junction capacitance (Note 1)	C_J	30.0							pF
Typical thermal resistance	R_{qJA}	55.0							°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-55 to +150							°C

Note: 1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

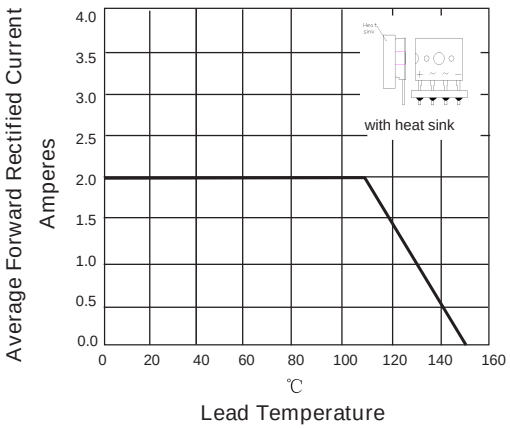


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

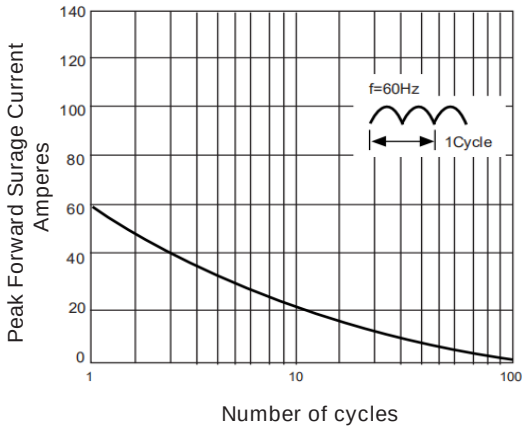


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

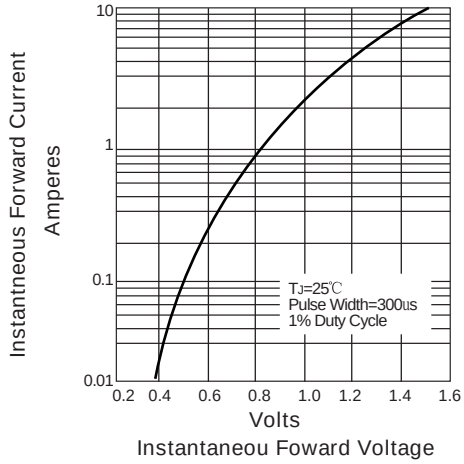
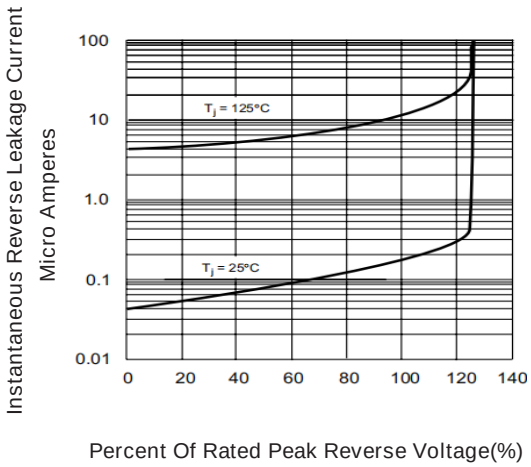
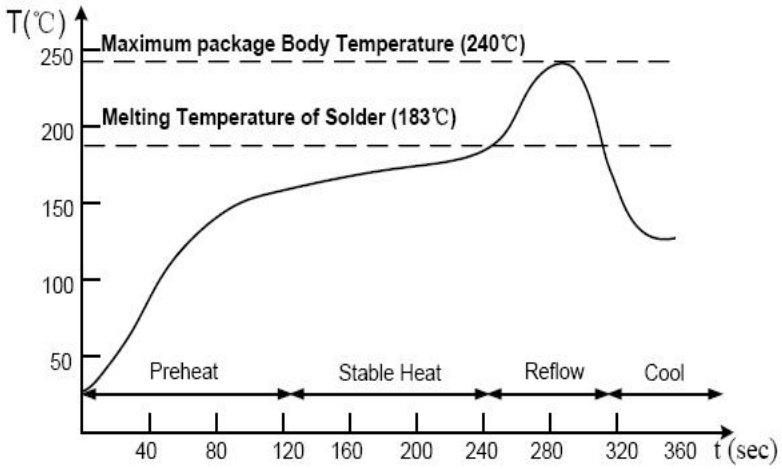


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
D3K	445*30.7*5.6	0.03	495*130*70	1.2	520*370*155	6

Please Read Carefully

Thank you for using or about to use our company's products. We suggest that you carefully read this material before use.

- Our company strives to provide users with higher quality products and services.
- Jiangsu POWERSi Microelectronics Co., Ltd. will periodically optimize its products and corresponding specifications, and may not be able to notify you in a timely manner. Please download the latest version regularly.
- Jiangsu POWERSi Microelectronics Co., Ltd. assumes no responsibility or risk for any use of its products for special purposes.
- Jiangsu POWERSi Microelectronics Co., Ltd. holds patent rights for its own products.
- Any semiconductor product has a certain possibility of failure or malfunction under specific conditions. The buyer is requested to comply with safety standards and take safety measures when using products from Jiangsu POWERSi Microelectronics Co., Ltd. for system design and complete machine manufacturing, in order to avoid situations that may cause personal injury or property damage!